

ABSTRACT

HEATING APPARATUS AND METHOD FOR SEMICONDUCTOR DEVICES

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A heating apparatus and method for heating a semiconductor device during bonding of electrical contacts onto the device is provided, which comprises a heating plate that is provided for heating the semiconductor device and a layer of compliant material extending over at least a portion of the heating plate for

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mounting the semiconductor device. A holding mechanism secures the semiconductor device on the layer of compliant material during bonding of electrical contacts onto the semiconductor device while it is being heated by the heating plate.

15 (FIG. 1)